

FEATURES

- ζ 26/28 dBm P1dB/PSAT
- ζ E2-band coverage
- ζ 33 dBm OIP3
- ζ 21 dB gain
- ζ Integrated PD & ED detectors

TYPICAL APPLICATIONS

- ζ Point-to-point communication
- ζ Instrumentation
- ζ Fiber over radio
- ζ 77 GHz automotive radar

DESCRIPTION

gAPZ0052 is a power amplifier in the 81-86 GHz frequency band suitable for E-band point-to-point communication and 77 GHz automotive radar. Integrated on chip are a high dynamic range output power detector, a wide band envelope detector and a temperature sensor. The PA utilizes multiple parallel transistors to increase efficiency and output power. The PA has high linearity, high efficiency, low input/output return loss and flat gain response.

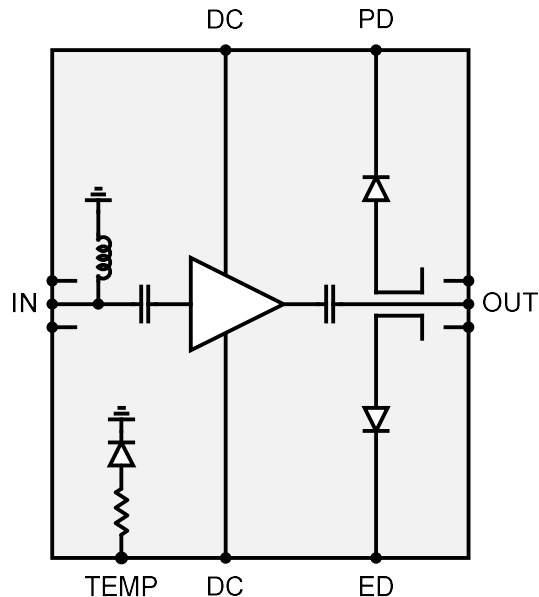


Figure 1. Block diagram of the PA.

ELECTRICAL PERFORMANCE

Table 1. Electrical performance $T_A=25^{\circ}\text{C}$

Parameter	Min	Typ	Max	Unit
Frequency	81 (75)		86 (87)	GHz
Gain		21		dB
Gain ripple				dB/GHz
P1dB		26		dBm
PSAT		28		dBm
OIP3		33		dBm
PAE			20	%
NF		6		dB
Input return loss	6			dB
Output return loss	6			dB
Power consumption		2500		mW

MEASURED PERFORMANCE

The chip has been measured on-wafer using CW and 2-tone input test signals. The PA uses typical bias settings if not specified differently.

Table 2. Test conditions

Parameter	Setting
RF input power	-10 dBm/tone
RF input frequency	83.5 GHz
Frequency separation	10 MHz
Temperature	+25°C

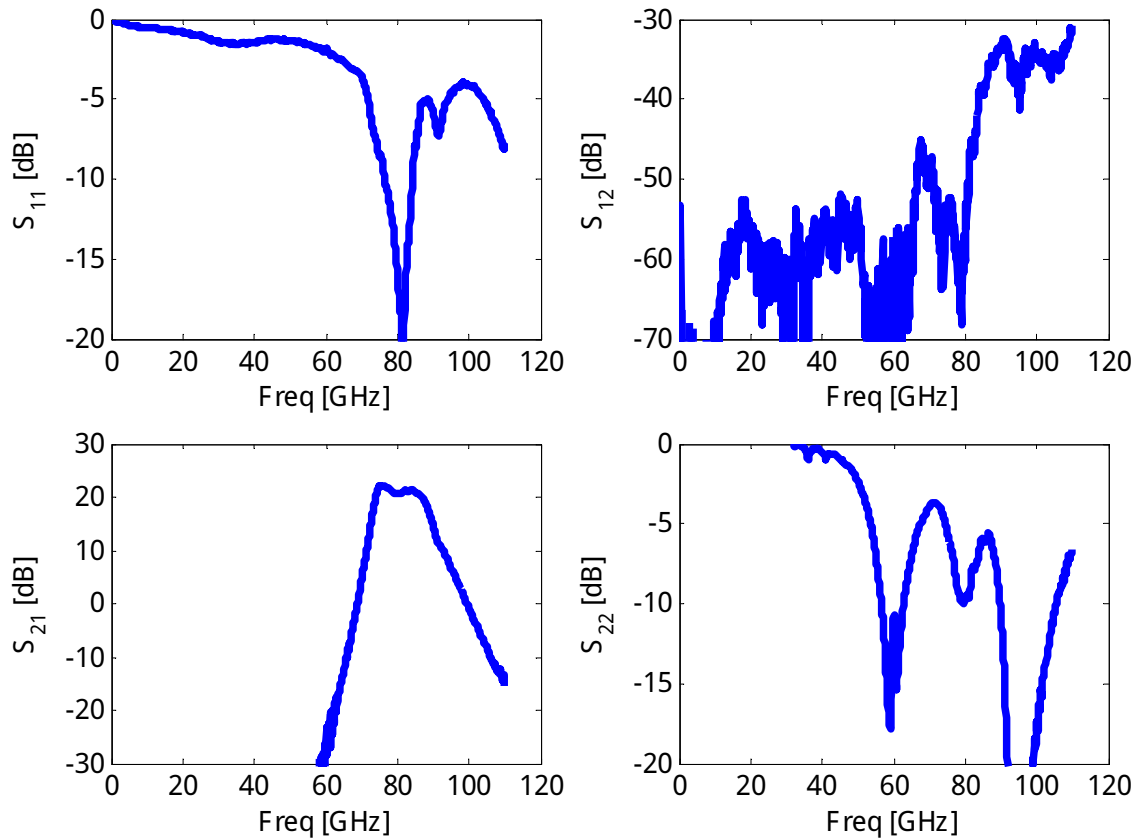
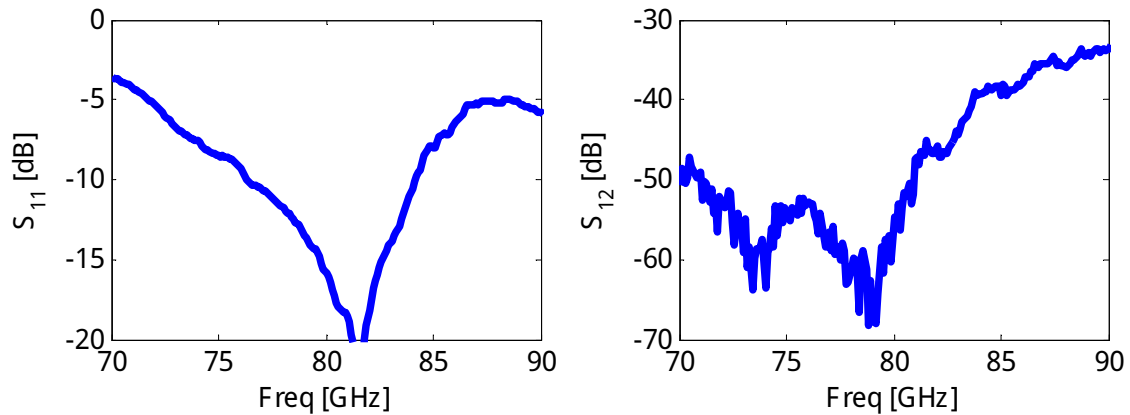


Figure 2. Small signal response from 0-120 GHz at nominal bias. (Upper left): Input return loss. (Upper right): Reverse isolation. (Lower left): Small-signal gain. (Lower right): Output return loss.



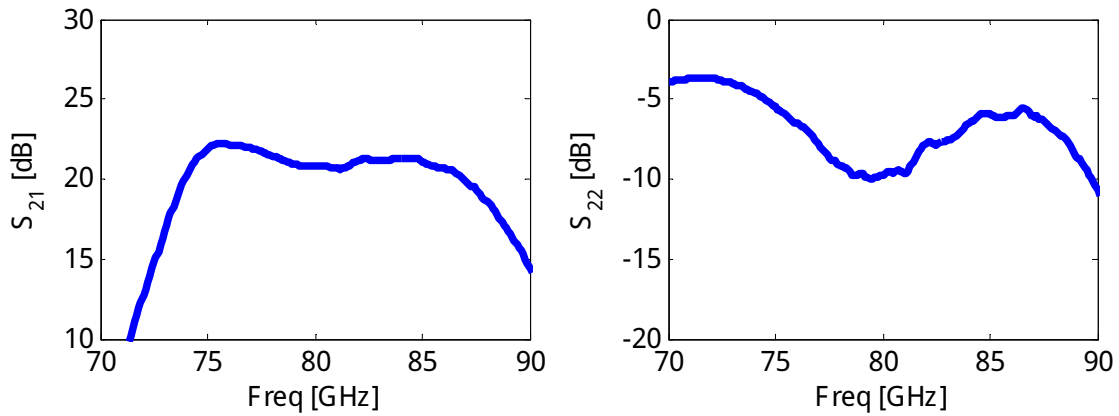


Figure 3. Small signal response within the E2-band at nominal bias. (Upper left): Input matching. (Upper right): Reverse isolation. (Lower left): Small-signal gain. (Lower right): Output return loss.

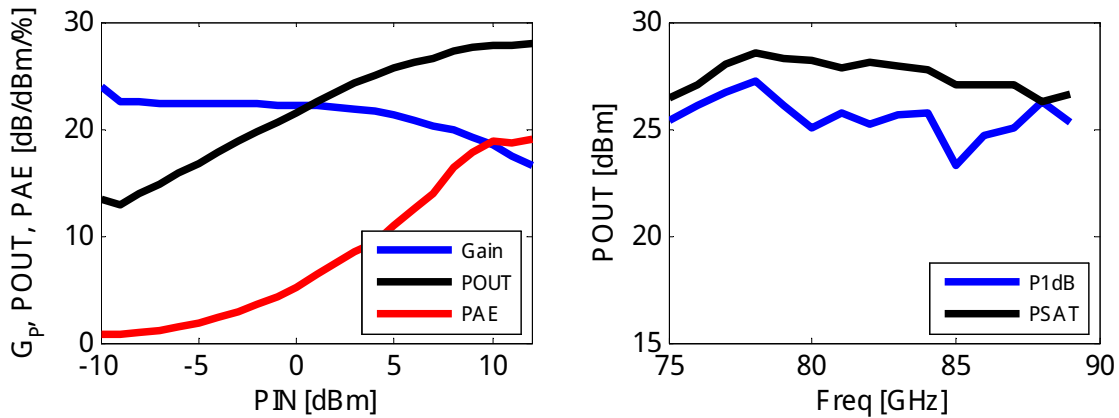


Figure 4. (Left): Output power, gain and PAE vs input power at 73 GHz. (Right): P1dB and PSAT vs freq.

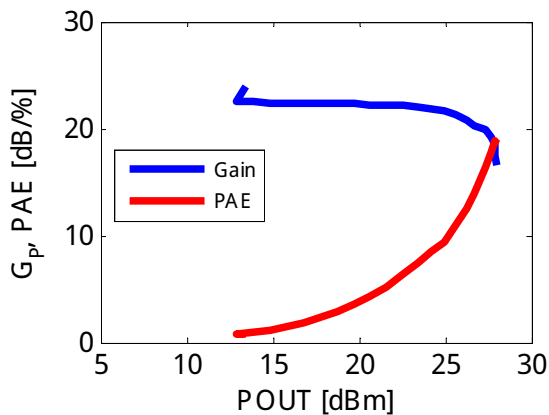


Figure 5. Efficiency vs output power at 83 GHz.

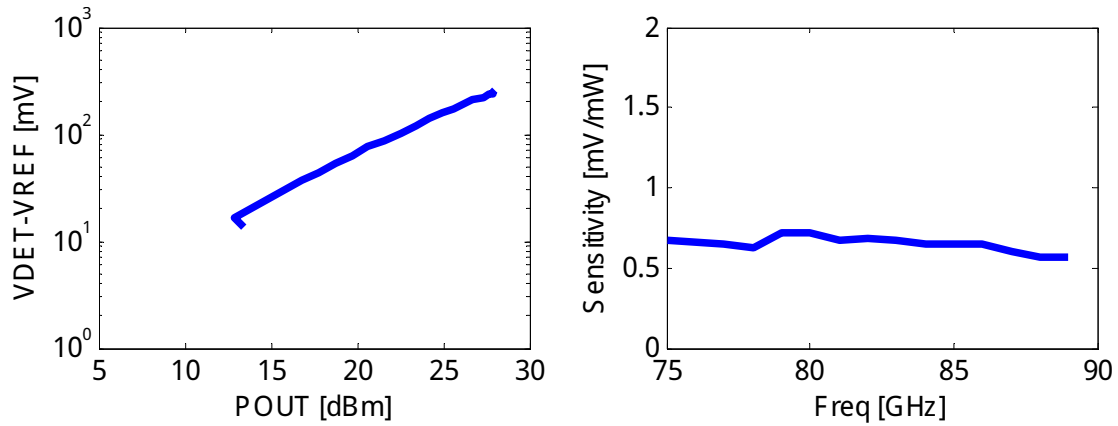


Figure 6. (Left): Power detector output voltage vs output power at 83 GHz and 1 G Ω load impedance. (Right): Power detector voltage sensitivity vs frequency at 20 dBm output power and 1 G Ω load impedance.

RECOMMENDED OPERATING CONDITIONS

Bias should first be applied to the gates (VG...) followed by the drains (VD...). The gate voltages must be adjusted within the min/max range indicated in Table 3-5 to obtain the specified drain currents. The drain currents are stated with on input signal.

Table 3. Electrical settings on connector P1

Connector P1	Pad No.	Bias settings (V/mA)			I/O
		Min	Typ	Max	
NC	1				NC
VD1_PA ^[1]	2	3.2	3.3 / 350	3.4	Input
VG1_PA ^[1]	3	-0.7	-0.5	-0.3	Input
VG2_PA ^[1]	4	-0.7	-0.5	-0.3	Input
GND	5				Ground
VD2_PA ^[1]	6	3.2	3.3 / 400	3.4	Input
VG_PD ^[2]	7	0.6	0.8	1.0	Input
VREF_PD	8	0	0.2		Output
VOUT_PD	9	0		2	Output

Table 4. Electrical settings on connector P2

Connector P2	Pad No.	Interface	I/O
GND	10		Ground
RF_OUT	11	Z ₀ = 50 Ohm, AC coupled	Output
GND	12		Ground

Table 5. Electrical settings on connector P3

Connector P3	Pad No.	Bias settings (V/mA)			I/O
		Min	Typ	Max	
VOUT_ED	13				Output
VD_ED	14	3.2	3.3	3.4	Input

¹ VG1, VG2, VD1 and VD2 are physically connected across the chip via P1 and P3. Both connectors must be biased for maximum performance. Total current for connectors P1 and P3 is specified.

^[2] Maximum sensitivity is achieved at threshold voltage.

VG_ED ^[2]	15	-1.0	-0.8	-0.6	Input
VD2_PA ^[1]	16	3.2	3.3 / 400	3.4	Input
GND	17				Ground
VG2_PA ^[1]	18	-0.7	-0.5	-0.2	Input
VG1_PA ^[1]	19	-0.7	-0.5	-0.2	Input
VD1_PA ^[1]	20	3.2	3.3 / 350	3.4	Input
VG_TEMP	21	3.2	3.3 / 1	3.4	I/O

Table 6. Electrical settings on connector P4

Connector P4	Pad No.	Interface	Function
GND	22		Ground
RF_IN	23	Z ₀ = 50 Ohm, AC coupled	Input
GND	24		Ground

ABSOLUTE MAXIMUM RATINGS

Table 7. Absolute maximum ratings

Gate-source voltage	-2 to +0.7 V
Drain-source voltage	4.5 V
Gate-drain breakdown voltage	8 V
ID1, ID2	720 mA
RF input power	+20 dBm
Operating temperature	-40 to + 85°C
Storage temperature	-65 to +150°C

OUTLINE DRAWING

Mechanical drawing with pad locations is also available in dxf-file format on the web. The substrate thickness is 50 μm (GaAs).

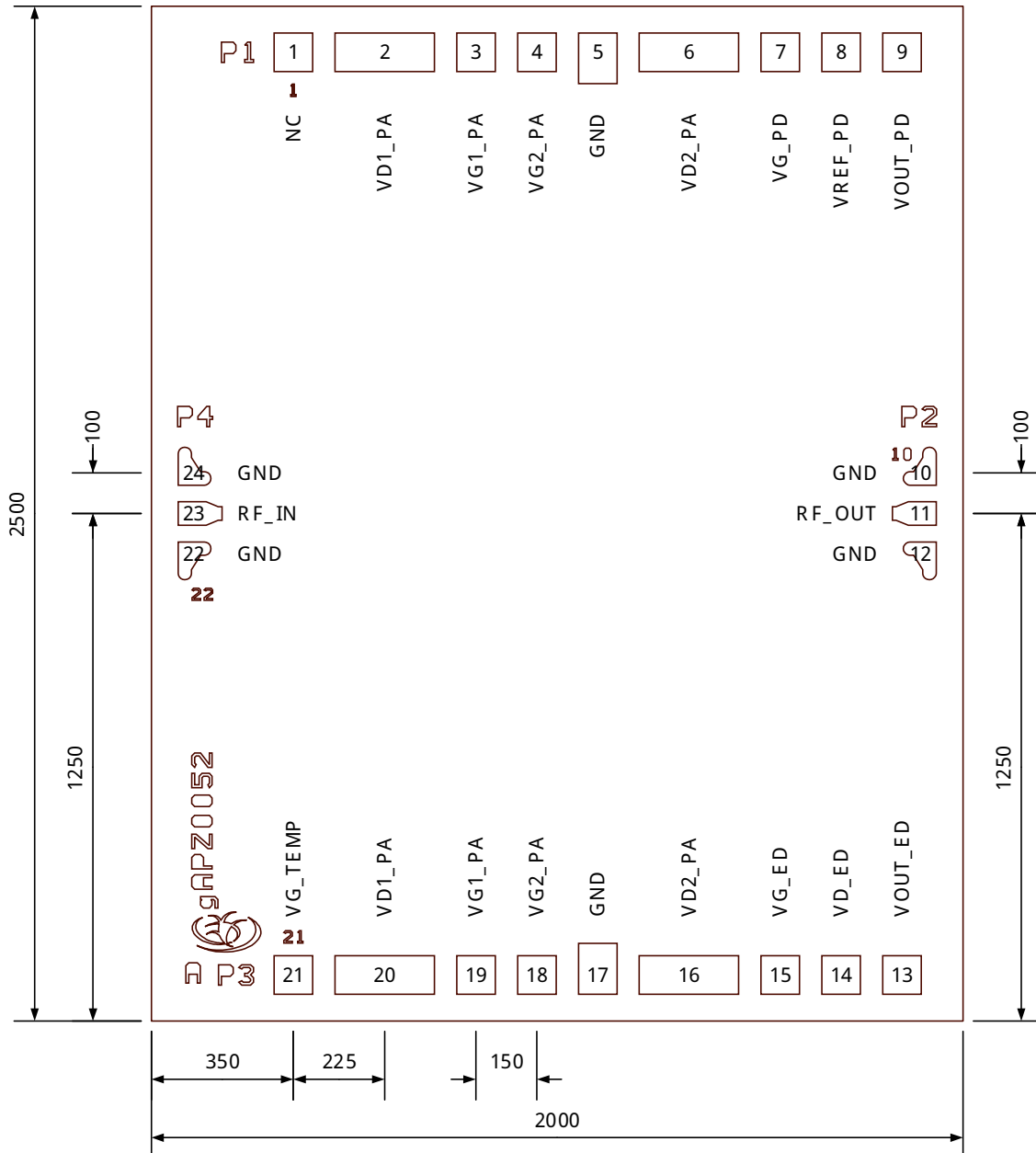


Figure 7. Outline drawing of the MMIC. Dimensions are in μm .